

Contents

1	Maximum ratings	3
2	Electrical characteristics	4
3	Pin connections	6
4	Current, voltage conventions and internal diagram	8
5	Switching time waveforms	10
6	Reverse polarity protection	13
7	Package mechanical data	14
7.1	Footprint recommended data	16
7.2	Tube shipment information	17
7.3	Tape and reel shipment information	18
8	Ordering information	20
9	Revision history	21

1 Maximum ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	DC supply voltage	45	V
$-I_{GND}$	DC ground pin reverse current TRAN ground pin reverse current (pulse duration < 1 ms)	-250 -6	mA A
I_{OUT}	DC output current	Internally limited	A
$-I_{OUT}$	Reverse DC output current	-2	A
I_{IN}	DC Input current	± 10	mA
V_{IN}	Input voltage range	$-3/+V_{CC}$	V
V_{ESD}	Electrostatic discharge ($R = 1.5\text{ k}\Omega$; $C = 100\text{ pF}$)	2000	V
P_{TOT}	Power dissipation at $T_C = 25\text{ }^\circ\text{C}$	96	W
EAS	Single pulse avalanche energy per channel 8 channels driven simultaneously ($T_{AMB} = 125\text{ }^\circ\text{C}$, $I_{OUT} = 0.6\text{ A}$ per channel)	1.15	J
T_J	Junction operating temperature	Internally limited	$^\circ\text{C}$
T_C	Case operating temperature	Internally limited	$^\circ\text{C}$
T_{STG}	Storage temperature	-40 to 150	$^\circ\text{C}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{th(JC)}$	Thermal resistance junction-case	Max. 1.3	$^\circ\text{C/W}$
$R_{th(JA)}$	Thermal resistance junction-ambient ⁽¹⁾	Max. 50	$^\circ\text{C/W}$

1. When mounted on FR4 printed circuit board with 0.5 cm^2 of copper area (at least $35\text{ }\mu\text{m}$ thick) connected to all TAB pins.

2 Electrical characteristics

(10.5 V < V_{CC} < 32 V; - 40 °C < T_J < 125 °C; unless otherwise specified)

Table 3. Power section

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{CC}	Operating supply voltage		10.5		45	V
V_{USD}	Undervoltage shutdown		7		10.5	V
R_{ON}	On state resistance	$I_{OUT} = 0.5$ A; $T_J = 25$ °C $I_{OUT} = 0.5$ A; $T_J = 125$ °C		150	185 280	mΩ mΩ
I_S	Supply current	OFF state; $V_{CC} = 24$ V $T_{CASE} = 25$ °C ON state (all channels ON) $V_{CC} = 24$ V, $T_{CASE} = 100$ °C			150 12	μA mA
I_{LGND}	Output current at turn-off	$V_{CC} = V_{STAT} = V_{IN} = V_{GND} = 24$ V $V_{OUT} = 0$ V			1	mA
$I_{L(off)}$	OFF state output current	$V_{IN} = V_{OUT} = 0$ V	0		5	μA
$V_{OUT(off)}$	OFF state output voltage	$V_{IN} = 0$ V, $I_{OUT} = 0$ A			3	V
$t_d(V_{CCon})$	Power-on delay time from V_{CC} rising edge	see Figure 7		1		ms

Table 4. Switching ($V_{CC} = 24$ V)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{ON}	Turn-on time	$R_L = 48$ Ω from 80% V_{OUT} (see Figure 6)		50	100	μs
t_{OFF}	Turn-off time	$R_L = 48$ Ω to 10% V_{OUT} (see Figure 6)		75	150	μs
$dV_{OUT}/dt(on)$	Turn-on voltage slope	$R_L = 48$ Ω from $V_{OUT} = 2.4$ V to $V_{OUT} = 19.2$ V (see Figure 6)		0.7		V/μs
$dV_{OUT}/dt(off)$	Turn-off voltage slope	$R_L = 48$ Ω from $V_{OUT} = 21.6$ V to $V_{OUT} = 2.4$ V (see Figure 6)		1.5		V/μs

Table 5. Input pin

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{INL}	Input low level				$V_{CC}/2-1$	V
I_{INL}	Low level input current	$V_{IN} = V_{CC} / 2 - 1 \text{ V}$	80		650	μA
V_{INH}	Input high level		$V_{CC}/2+1$			V
I_{INH}	High level input current	$V_{IN} = V_{CC} / 2 + 1 \text{ V}$		150	260	μA
$V_{I(HYST)}$	Input hysteresis voltage			0.6		V
I_{IN}	Input current	$V_{IN} = V_{CC} = 32 \text{ V}$			300	μA

Table 6. Protection

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
T_{CSD}	Case shutdown temperature		125	130	135	$^{\circ}\text{C}$
T_{CR}	Case reset temperature		110			$^{\circ}\text{C}$
T_{CHYST}	Case thermal hysteresis		7	15		$^{\circ}\text{C}$
T_{TSD}	Junction shutdown temperature		150	175	200	$^{\circ}\text{C}$
T_R	Junction reset temperature		135			$^{\circ}\text{C}$
T_{HYST}	Junction thermal hysteresis		7	15		$^{\circ}\text{C}$
I_{lim}	DC short-circuit current	$V_{CC} = 24 \text{ V}$; $R_{LOAD} = 10 \text{ m}\Omega$	1		1.7	A
V_{demag}	Turn-off output clamp voltage	$I_{OUT} = 0.5 \text{ A}$; $L = 6 \text{ mH}$	$V_{CC}-57$	$V_{CC}-52$	$V_{CC}-47$	V

Table 7. Status pin

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{HSTAT}	High level output current	$V_{CC} = 18...32 \text{ V}$; $R_{STAT} = 1 \text{ k}\Omega$ (fault condition)	2	3	4	mA
I_{LSTAT}	Leakage current	Normal operation; $V_{CC} = 32 \text{ V}$			0.1	μA
V_{CLSTAT}	Clamp voltage	$I_{STAT} = 1 \text{ mA}$ $I_{STAT} = -1 \text{ mA}$	6.0	6.8 -0.7	8.0	V V

3 Pin connections

Figure 2. Connection diagram (top view)

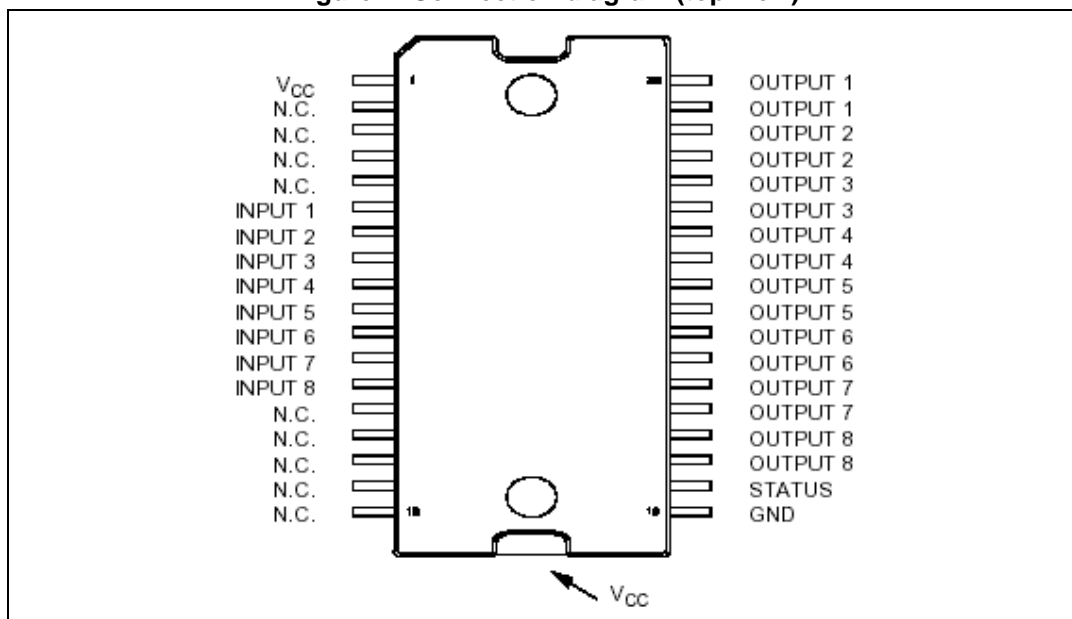


Table 8. Pin functions

Pin N°	Symbol	Function
TAB	V_{CC}	Positive power supply voltage
1	V_{CC}	Positive power supply voltage
2,3,4,5	NC	Not connected
6	Input 1	Input of channel 1
7	Input 2	Input of channel 2
8	Input 3	Input of channel 3
9	Input 4	Input of channel 4
10	Input 5	Input of channel 5
11	Input 6	Input of channel 6
12	Input 7	Input of channel 7
13	Input 8	Input of channel 8
14,15,16,17,18	NC	Not connected
19	GND	Logic ground
20	STATUS	Common open source diagnostic for overtemperature
21,22	Output 8	High-side output of channel 8
23,24	Output 7	High-side output of channel 7
25,26	Output 6	High-side output of channel 6

Table 8. Pin functions (continued)

Pin N°	Symbol	Function
27,28	Output 5	High-side output of channel 5
29,30	Output 4	High-side output of channel 4
31,32	Output 3	High-side output of channel 3
33,34	Output 2	High-side output of channel 2
35,36	Output 1	High-side output of channel 1

4 Current, voltage conventions and internal diagram

Figure 3. Current and voltage conventions

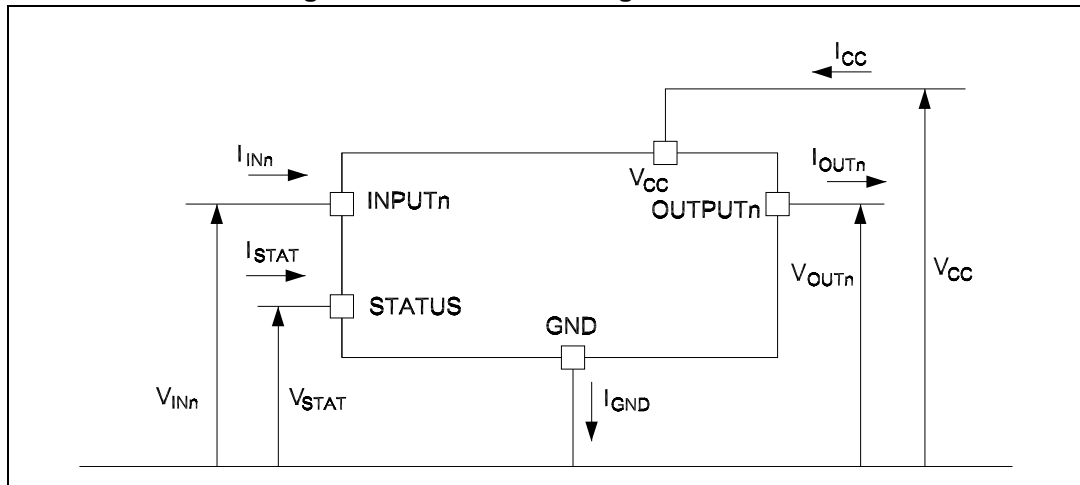


Figure 4. Equivalent internal block diagram (same structure for all channels)

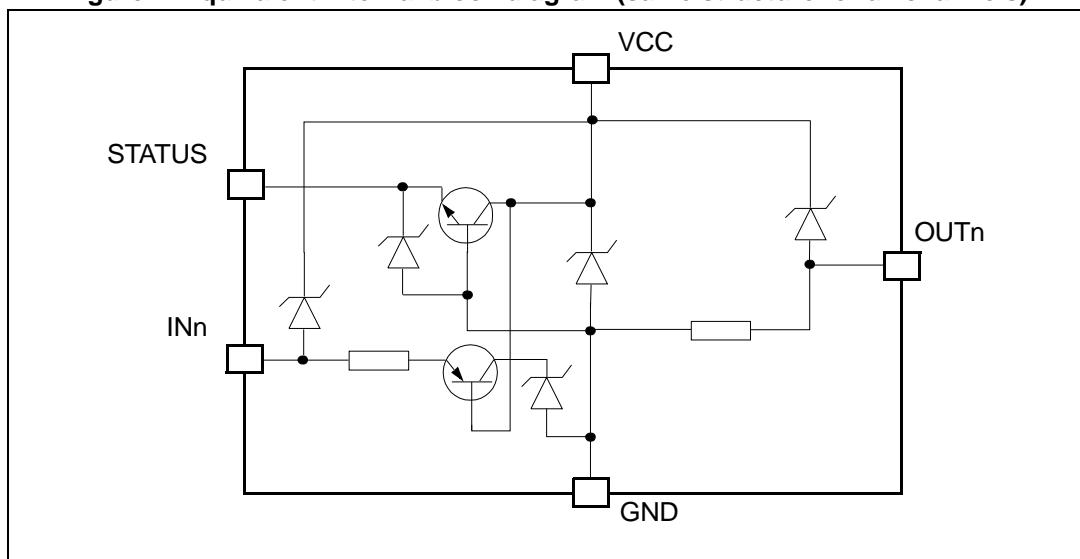


Figure 5. Application example

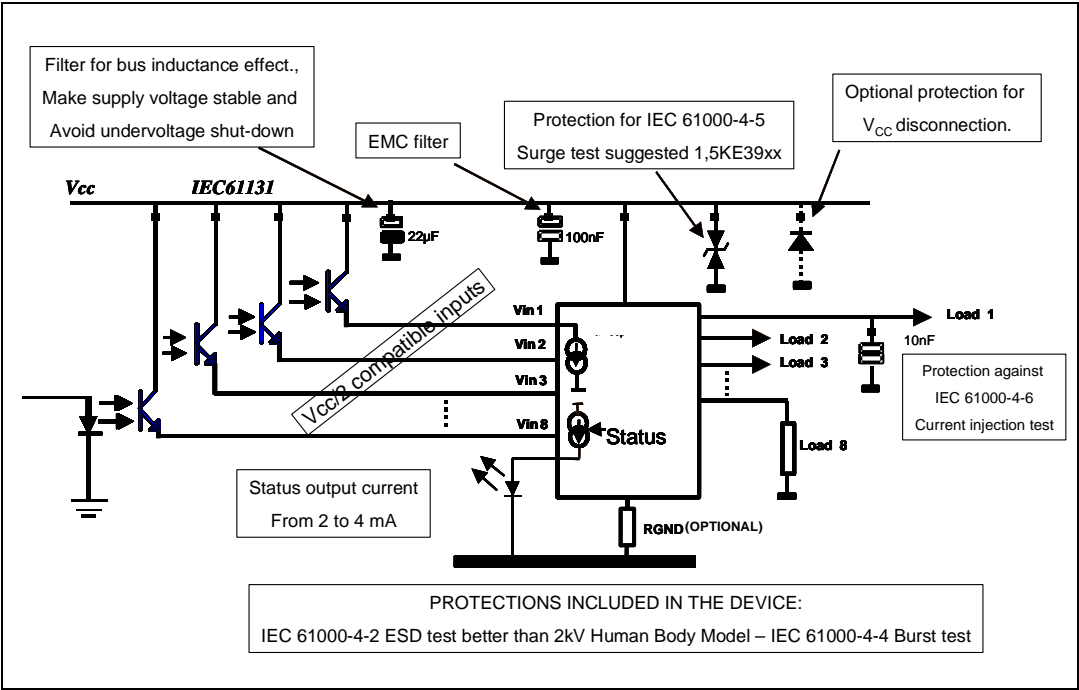


Table 9. Truth table

Conditions	INPUTn	OUTPUTn	STATUS
Normal operation	L H	L H	L L
Current limitation	L H	L X	L L
Overtemperature (see waveforms 3, 4 Figure 8) -> T _J > T _{TSD}	L H	L L	L H
Undervoltage	L H	L L	X X

5 Switching time waveforms

Figure 6. Turn-on and turn-off

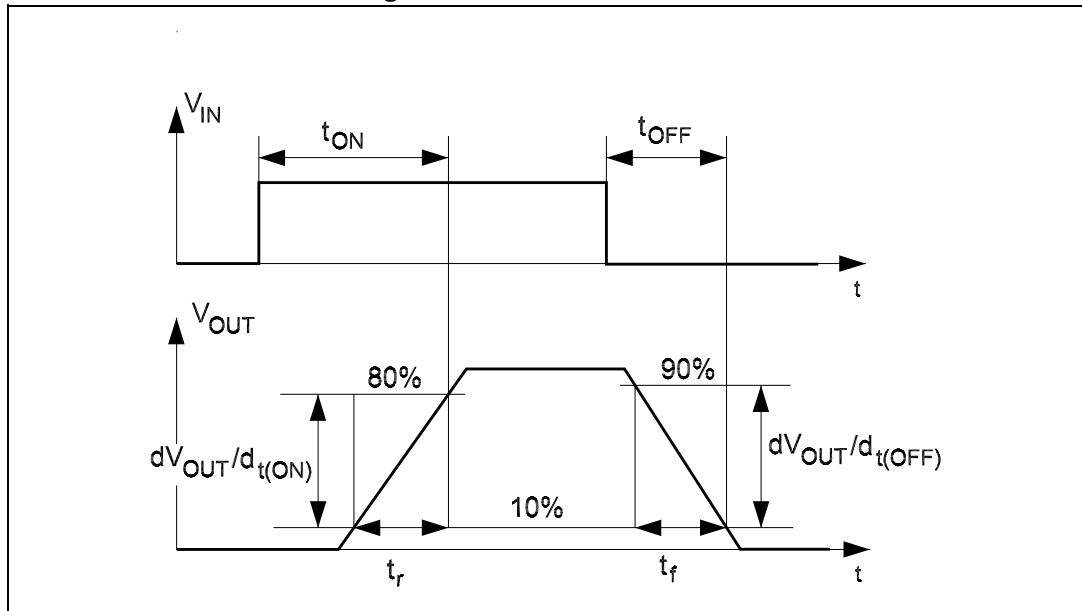


Figure 7. V_{CC} turn-on

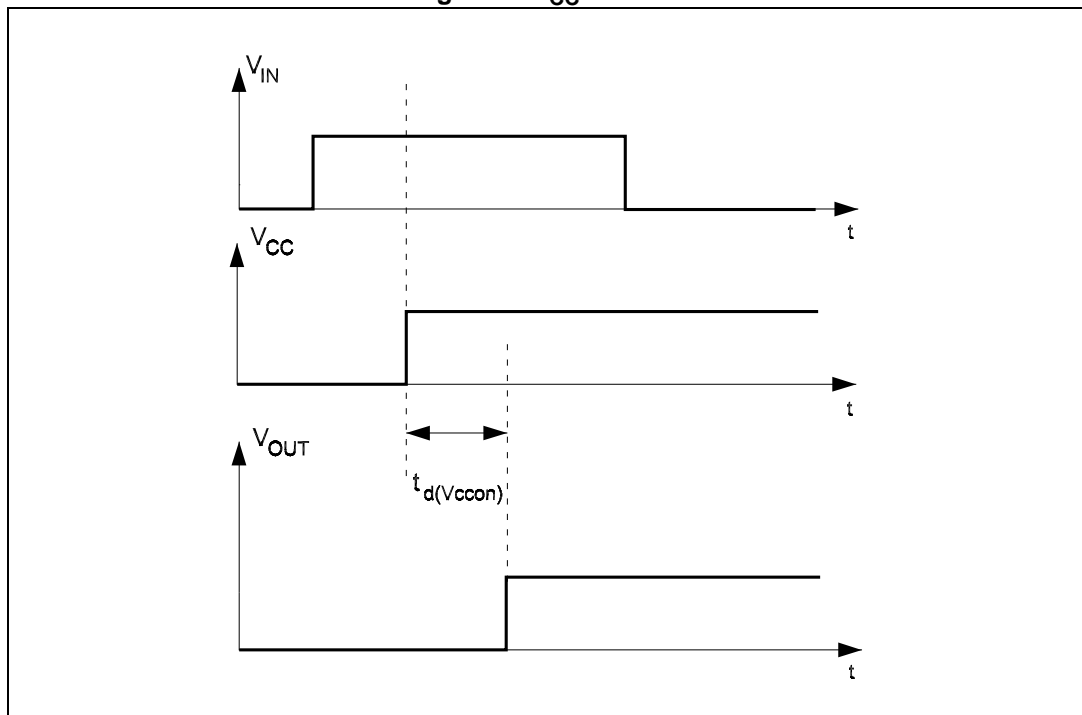


Figure 8. Waveforms

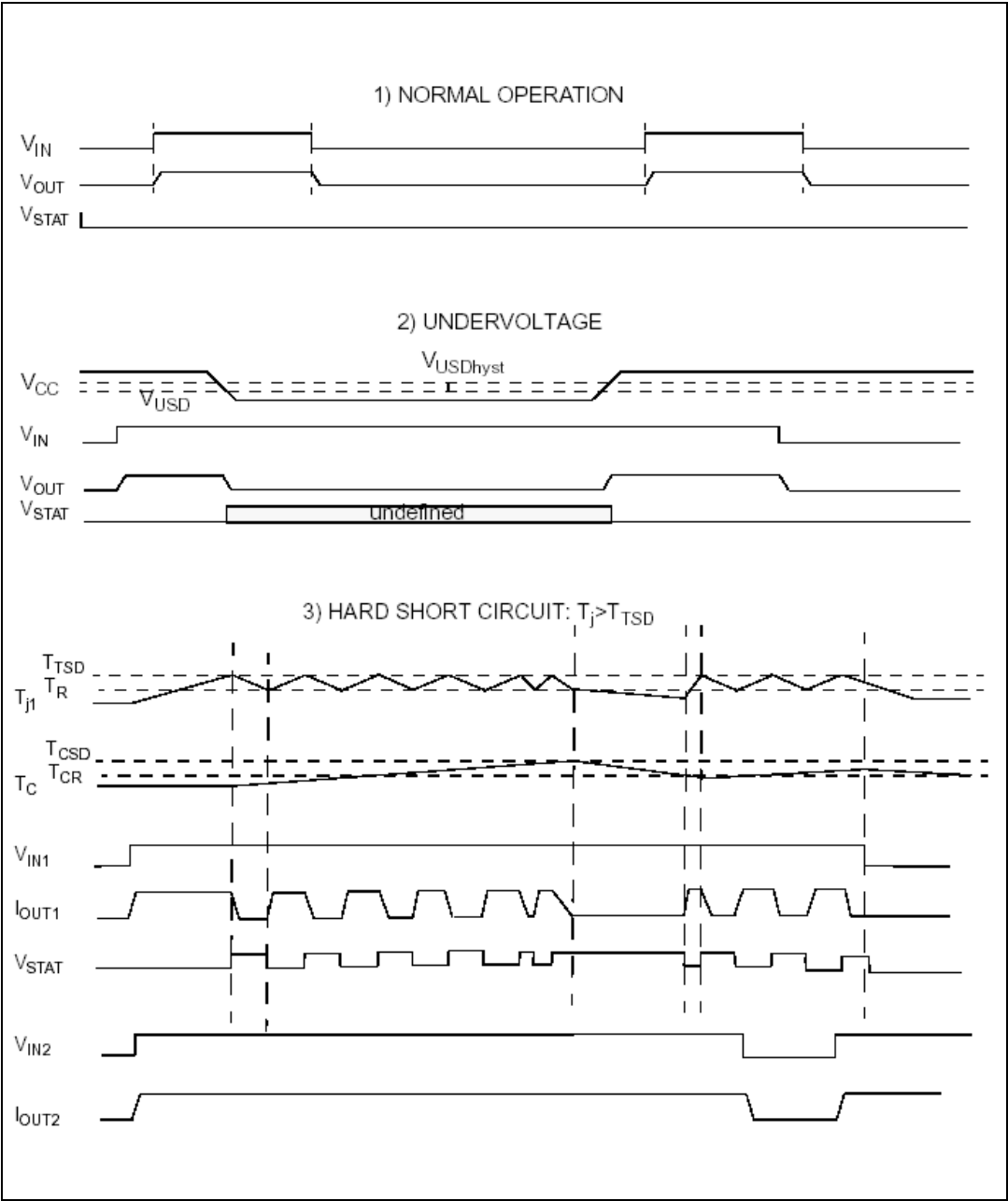
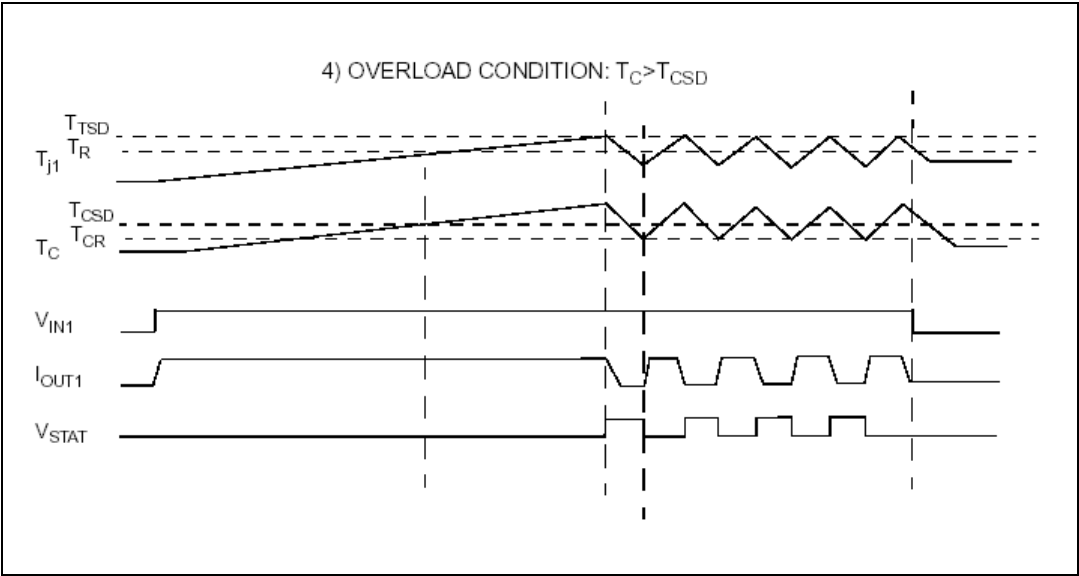


Figure 9. Waveforms (continued)



6 Reverse polarity protection

Reverse polarity protection can be implemented on board using two different solutions:

1. Placing a resistor (R_{GND}) between IC GND pin and load GND
2. Placing a diode between IC GND pin and load GND

If option 1 is selected, the minimum resistance value has to be selected according to the following equation:

Equation 1

$$R_{GND} \geq V_{CC}/I_{GND}$$

where I_{GND} is the DC reverse ground pin current and can be found in [Section 1: Maximum ratings](#) of this datasheet.

Power dissipated by R_{GND} (when $V_{CC} < 0$: during reverse polarity situations) is:

Equation 2

$$P_D = (V_{CC})^2/R_{GND}$$

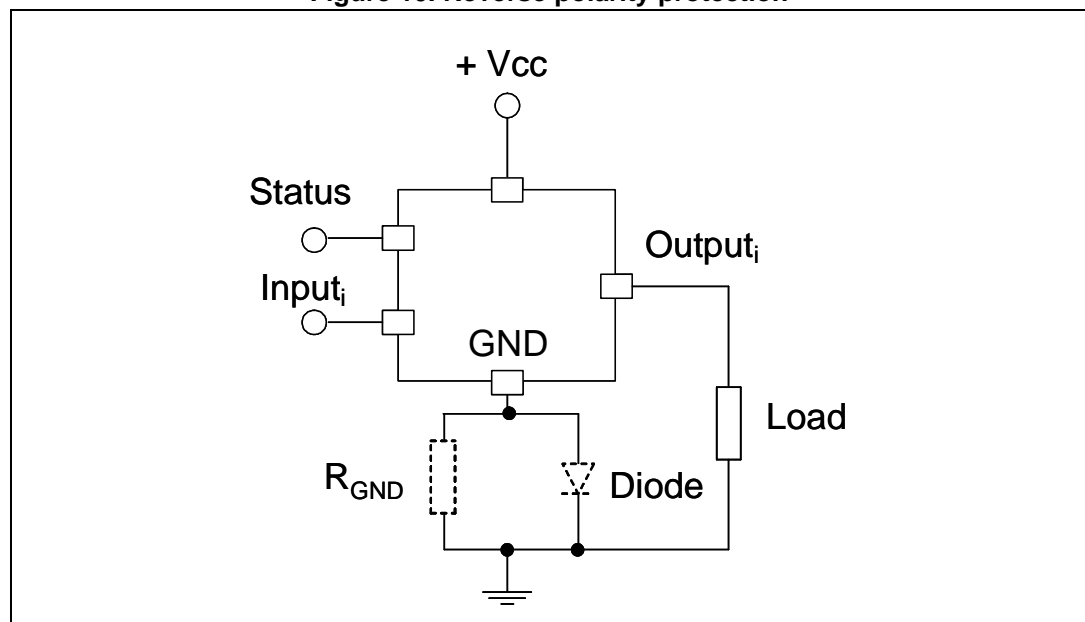
If option 2 is selected, the diode has to be chosen by taking into account $V_{RRM} > |V_{CC}|$ and its power dissipation capability:

Equation 3

$$P_D \geq I_S \cdot V_f$$

Note: In normal conditions (no reverse polarity) due to the diode, there is a voltage drop between GND of the device and GND of the system.

Figure 10. Reverse polarity protection



This schematic can be used with any kind of load.

7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Figure 11. PowerSO-36 drawings

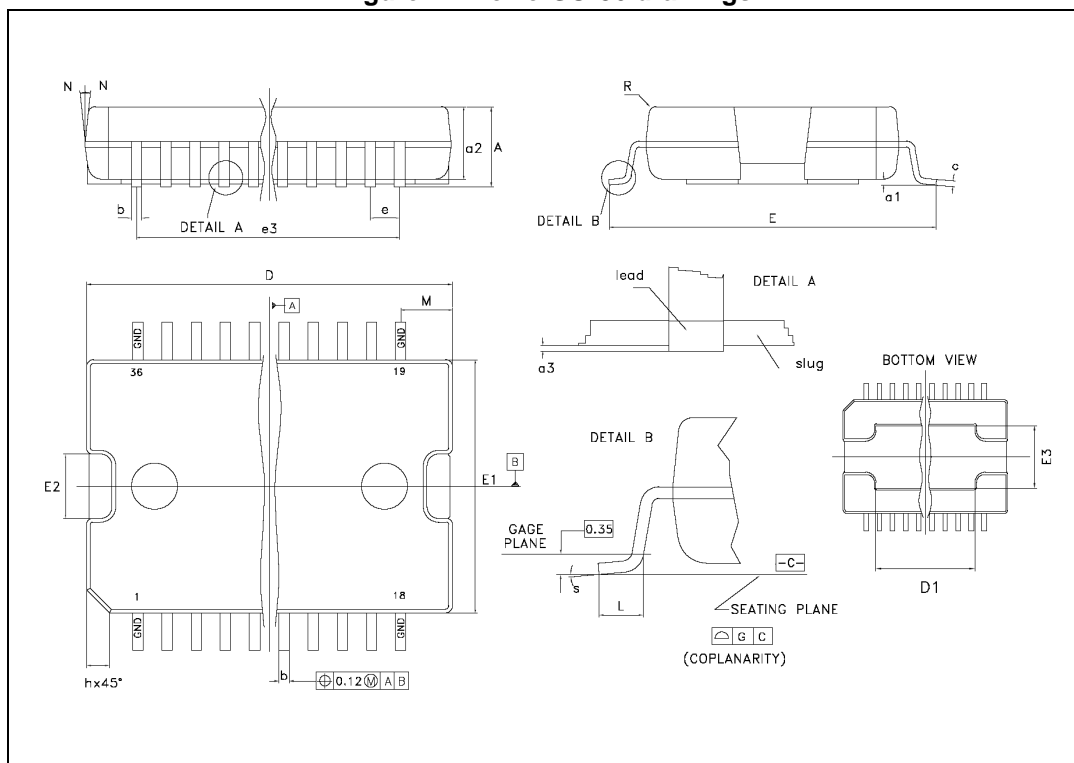


Table 10. PowerSO-36 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			3.60
a1	0.10		0.30
a2			3.30
a3	0		0.10
b	0.22		0.38
c	0.23		0.32
D (1)	15.80		16.00
D1	9.40		9.80
E	13.90		14.50
E1 (1)	10.90		11.10
E2			2.90
E3	5.8		6.2
e		0.65	
e3		11.05	
G	0		0.10
H	15.50		15.90
h			1.10
L	0.80		1.10
N			10°
S	0°		8°

7.1 Footprint recommended data

Figure 12. Footprint recommended data

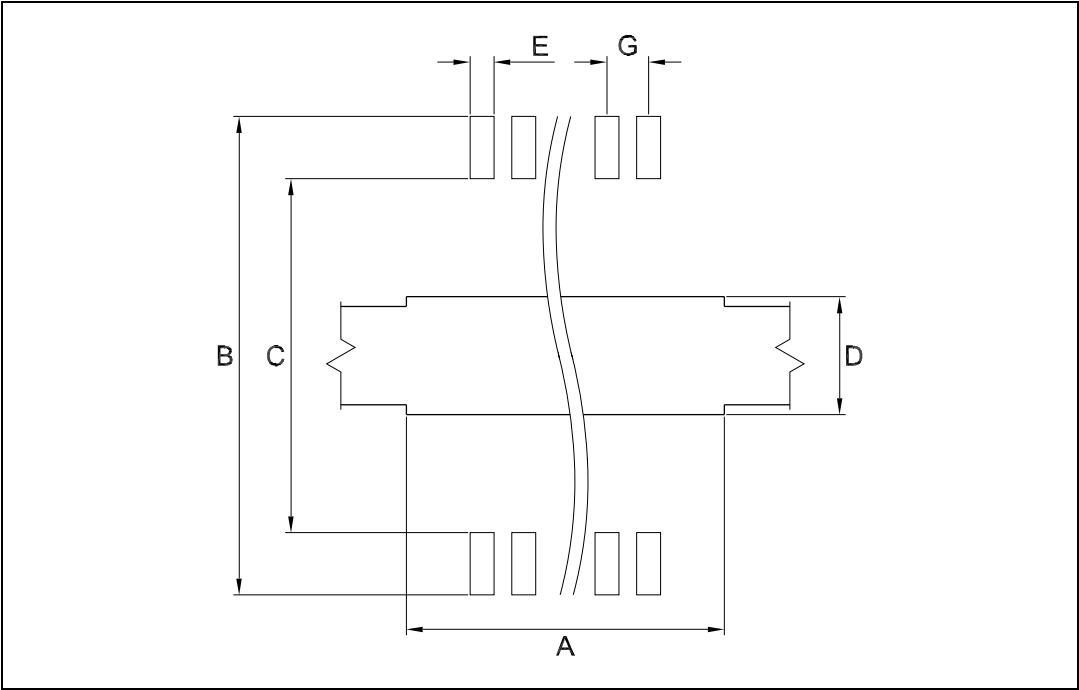


Table 11. Footprint data

Dim.	mm
A	9.5
B	14.7-15.0
C	12.5-12.7
D	6.3
E	0.42
G	0.65

7.2 Tube shipment information

Figure 13. Tube shipment information

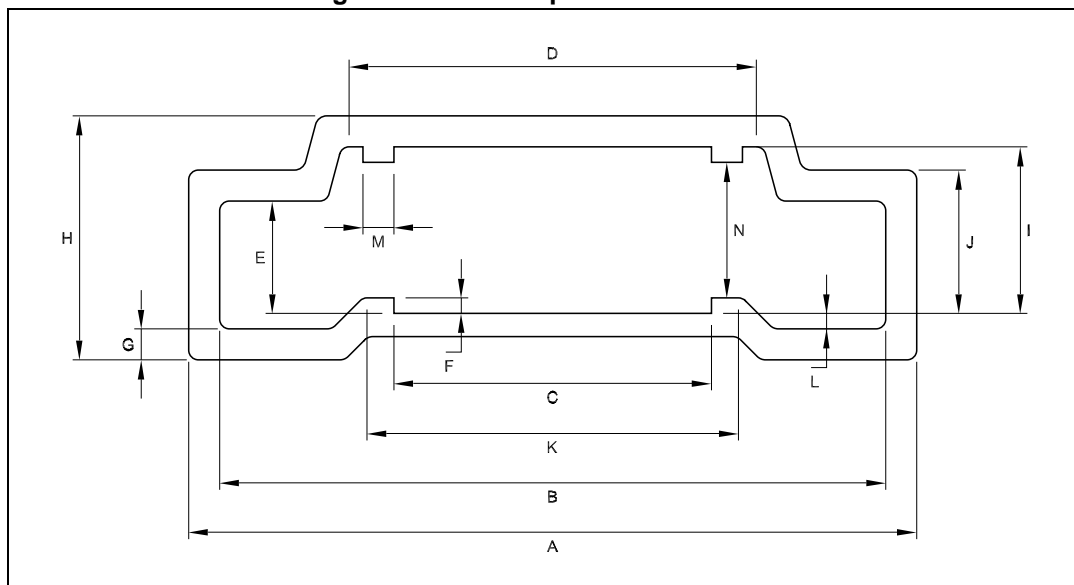


Table 12. Tube mechanical data

Dim.	mm
A	18.80
B	17.2 ±0.2
C	8.20 ±0.2
D	10.90 ±0.2
E	2.90 ±0.2
F	0.40
G	0.80
H	6.30
I	4.30 ±0.2
J	3.7 ±0.2
K	9.4
L	0.40
M	0.80
N	3.50 ±0.2

Base quantity 31 pcs

Bulk quantity 310 pcs

7.3 Tape and reel shipment information

Figure 14. Tape specifications

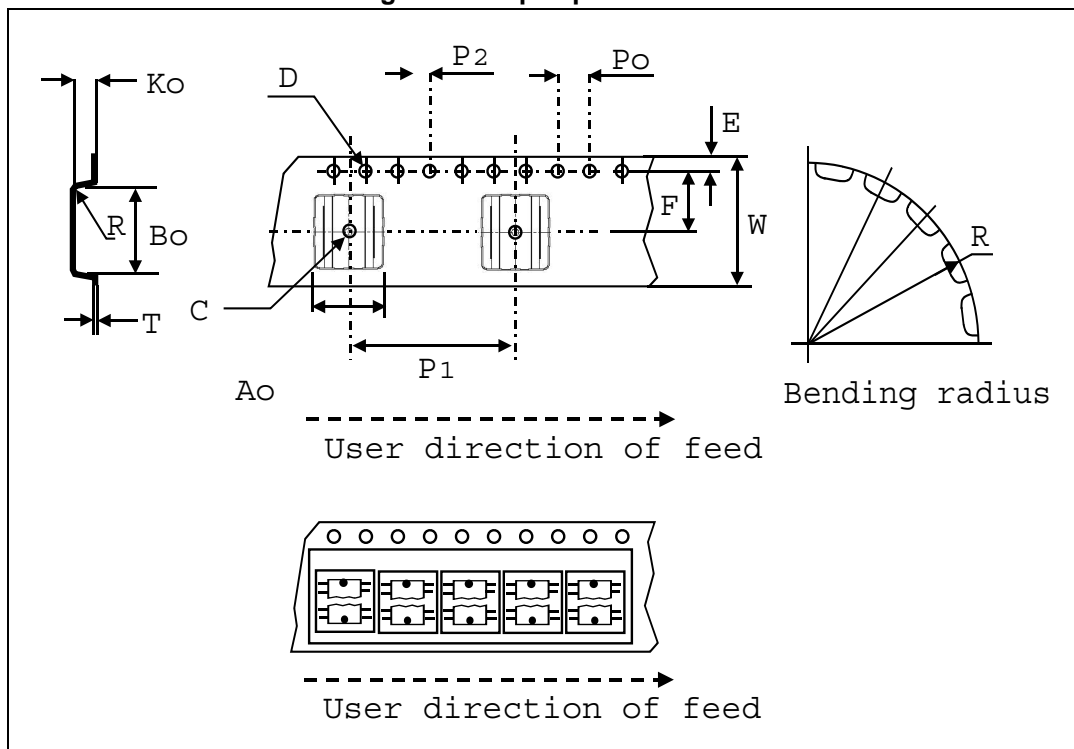


Table 13. Tape mechanical data

Dim.	mm
D	1.50 +0.1/0
E	1.75 ±0.1
Po	4.00 ±0.1
T max.	0.40
D1 min.	1.50
F	11.5 ±0.05
K max.	6.50
P2	2.00 ±0.1
R	50
W	24.00 ±0.30
P1	24.00
Ao, Bo, Ko	0.05 min to 1.0 max.

Base quantity 600 pcs

Bulk quantity 600 pcs

Figure 15. Reel specifications

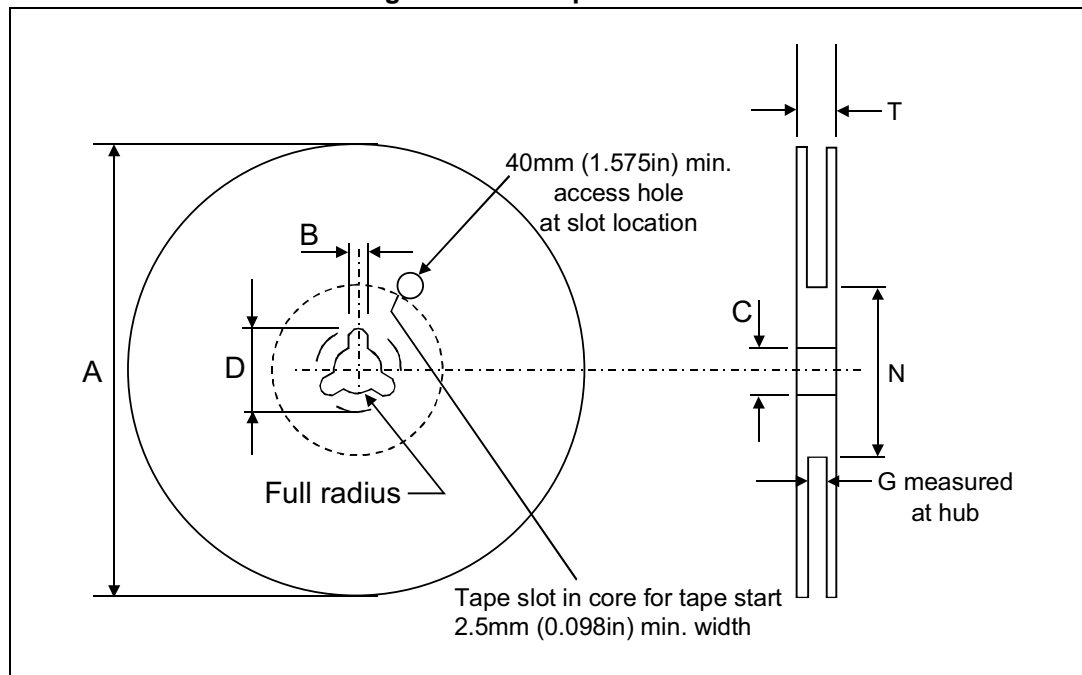


Table 14. Reel mechanical data

Dim.	mm
Tape size	24.0 ±0.30
A max.	330.0
B min.	1.5
C	13.0 ±0.20
D min.	20.2
N min.	60
G	24.4 +2/-0
T max.	30.4

8 Ordering information

Table 15. Order code

Order code	Package	Packaging
VN808-32-E	PowerSO-36	Tube
VN808TR-32-E	PowerSO-36	Tape and reel

9 Revision history

Table 16. Document revision history

Date	Revision	Changes
25-Jan-2008	1	Initial release
07-Jul-2008	2	Added Section 6 on page 13
04-Aug-2008	3	Added: Figure 12: Footprint recommended data
25-Aug-2009	4	Updated Section 6: Reverse polarity protection
24-Feb-2010	5	Updated Section 7: Package mechanical data
07-Dec-2012	6	Added max. value to I_{INL} parameter in Table 5 . Minor text changes.
01-Jul-2013	7	Updated Section 7.1: Footprint recommended data .
19-Dec-2013	8	Replaced L_{MAX} parameter by EAS parameter in Table 1 . Added T_J condition to Table 3 . Updated Section 6 .

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2013 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com